

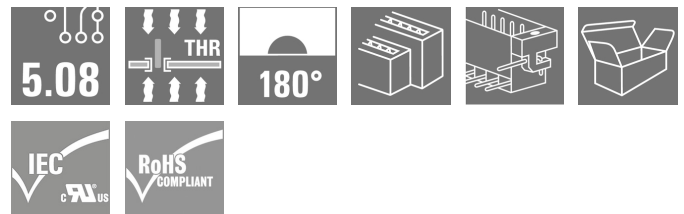
SLDV-THR 5.08/32 FLF4.5SN SW**Weidmüller Interface GmbH & Co. KG**

Klingenbergstraße 26

D-32758 Detmold

Germany

www.weidmueller.com

Product image

High-temperature resistant, double level, laterally offset, male connector with flange or solder flange. 1.5 mm solder pin is suitable for reflow soldering. 3.2 mm solder pin suitable for reflow and wave soldering. The pin headers provide space for labelling and can be coded.

General ordering data

Version	PCB plug-in connector, male header, Flange / Solder flange, THT/THR solder connection, 5.08 mm, Number of poles: 32, 180°, Solder pin length (l): 4.5 mm, tinned, black, Box
Order No.	1934150000
Type	SLDV-THR 5.08/32 FLF4.5SN SW
GTIN (EAN)	4032248589500
Qty.	12 pc(s).
Product data	IEC: 400 V / 15 A UL: 300 V / 10 A
Packaging	Box

Creation date May 11, 2025 8:18:03 PM CEST

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Technical data

Dimensions and weights

Depth	23.67 mm	Depth (inches)	0.932 inch
Height	30.66 mm	Height (inches)	1.207 inch
Height of lowest version	26.16 mm	Width	91.44 mm
Width (inches)	3.6 inch	Net weight	26.4 g

System specifications

Product family	OMNIMATE Signal - series BL/SL 5.08	Type of connection	Board connection
Mounting onto the PCB	THT/THR solder connection	Pitch in mm (P)	5.08 mm
Pitch in inches (P)	0.2 "	Outgoing elbow	180°
Number of poles	32	Number of solder pins per pole	1
Solder pin length (l)	4.5 mm	Solder pin length tolerance	0 / -0.3 mm
Solder pin dimensions	d = 1.2 mm, Octagonal	Solder eyelet hole diameter (D)	1.5 mm
Solder eyelet hole diameter tolerance (D)+	0,1 mm	L1 in mm	76.2 mm
L1 in inches	3 "	Pin series quantity	2
Touch-safe protection acc. to DIN VDE 57 106	finger-safe unplugged/ back-of-hand-safe plugged	Touch-safe protection acc. to DIN VDE 0470	IP20 plugged/ IP10 unplugged
Protection degree	IP20	Volume resistance	≤5 mΩ
Can be coded	Yes	Plugging force/pole, max.	10 N
Pulling force/pole, max.	7.5 N		

Material data

Insulating material	LCP GF	Colour	black
Colour chart (similar)	RAL 9011	Insulating material group	IIIa
Comparative Tracking Index (CTI)	≥ 175	Moisture Level (MSL)	1
UL 94 flammability rating	V-0	Contact material	Cu-alloy
Contact surface	tinned	Layer structure of solder connection	1...3 µm Ni / 2...4 µm Sn matt
Layer structure of plug contact	1...3 µm Ni / 2...4 µm Sn matt	Storage temperature, min.	-40 °C
Storage temperature, max.	70 °C	Operating temperature, max.	100 °C
Temperature range, installation, max.	100 °C		

Rated data acc. to IEC

tested acc. to standard	IEC 60664-1, IEC 61984	Rated current, min. number of poles (Tu=20°C)	15 A
Rated current, max. number of poles (Tu=20°C)	10.5 A	Rated current, min. number of poles (Tu=40°C)	13 A
Rated current, max. number of poles (Tu=40°C)	9 A	Rated voltage for surge voltage class / pollution degree II/2	400 V
Rated voltage for surge voltage class / pollution degree III/2	320 V	Rated voltage for surge voltage class / pollution degree III/3	250 V
Rated impulse voltage for surge voltage class/ pollution degree II/2	4 kV	Rated impulse voltage for surge voltage class/ pollution degree III/2	4 kV
Rated impulse voltage for surge voltage class/ contamination degree III/3	4 kV	Short-time withstand current resistance	1 x 1s with 120 A

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Technical data

Rated data acc. to CSA

Institute (CSA)



Certificate No. (CSA)

200039-1121690

Rated voltage (Use group B / CSA) 300 V

Rated voltage (Use group D / CSA) 300 V

Rated current (Use group B / CSA) 10 A

Rated current (Use group D / CSA) 10 A

Reference to approval values

Specifications are maximum values, details - see approval certificate.

Rated data acc. to UL 1059

Rated voltage (Use group B / UL 1059) 300 V

Rated voltage (Use group D / UL 1059) 300 V

Rated current (Use group B / UL 1059) 10 A

Rated current (Use group D / UL 1059) 10 A

Packing

Packaging Box

VPE length 347 mm

VPE width 139 mm

VPE height 45 mm

Classifications

ETIM 6.0

EC002637

ETIM 7.0

EC002637

ETIM 8.0

EC002637

ETIM 9.0

EC002637

ETIM 10.0

EC002637

ECLASS 9.0

27-44-04-02

ECLASS 9.1

27-44-04-02

ECLASS 10.0

27-44-04-02

ECLASS 11.0

27-46-02-01

ECLASS 12.0

27-46-02-01

ECLASS 13.0

27-46-02-01

ECLASS 14.0

27-46-02-01

ECLASS 15.0

27-46-02-01

Environmental Product Compliance

RoHS Compliance Status

Compliant without exemption

REACH SVHC

No SVHC above 0.1 wt%

Important note

IPC conformity

Conformity: The products are developed, manufactured and delivered according international recognized standards and norms and comply with the assured properties in the data sheet resp. fulfill decorative properties in accordance with IPC-A-610 "Class 2". Further claims on the products can be evaluated on request.

Notes

- Rated current related to rated cross-section & min. No. of poles.
- Spacing between rows: see hole layout
- P on drawing = pitch
- Rated data refer only to the component itself. Clearance and creepage distances to other components are to be designed in accordance with the relevant application standards.
- In accordance with IEC 61984, OMNIMATE-connectors are connectors without breaking capacity (COC). During designated use, connectors are not allowed to be engaged or disengaged when live or under load
- Long term storage of the product with average temperature of 50 °C and maximum humidity 70%, 36 months

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www.weidmueller.com**Technical data****Approvals**

Approvals



Approvals MAMID

https://mdcop.weidmueller.com/mediadelivery/rendition/900_319226/-T1z1mm-S800/

ROHS

Conform

Downloads

Engineering Data

[CAD data – STEP](#)

Product Change Notification

[Anpassung Verpackung SLDV-THR 5.08](#)[Change of packaging _ SLDV-THR 5.08](#)

Catalogues

[Catalogues in PDF-format](#)

Brochures

[FL DRIVES EN](#)[FL DRIVES DE](#)

White paper surface mount technology

[Download Whitepaper](#)

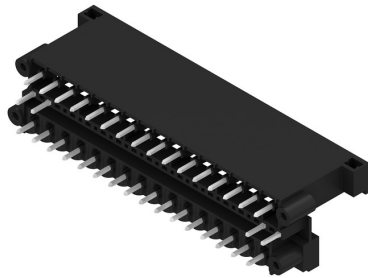
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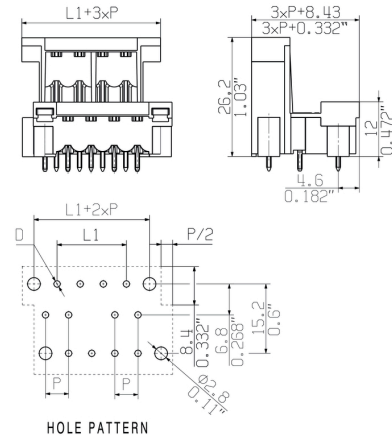
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Drawings

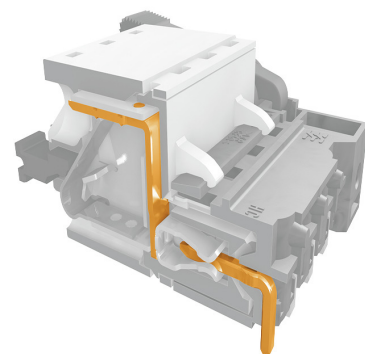
Product image



Dimensional drawing



Product benefits



Safe power transmission
Proven properties

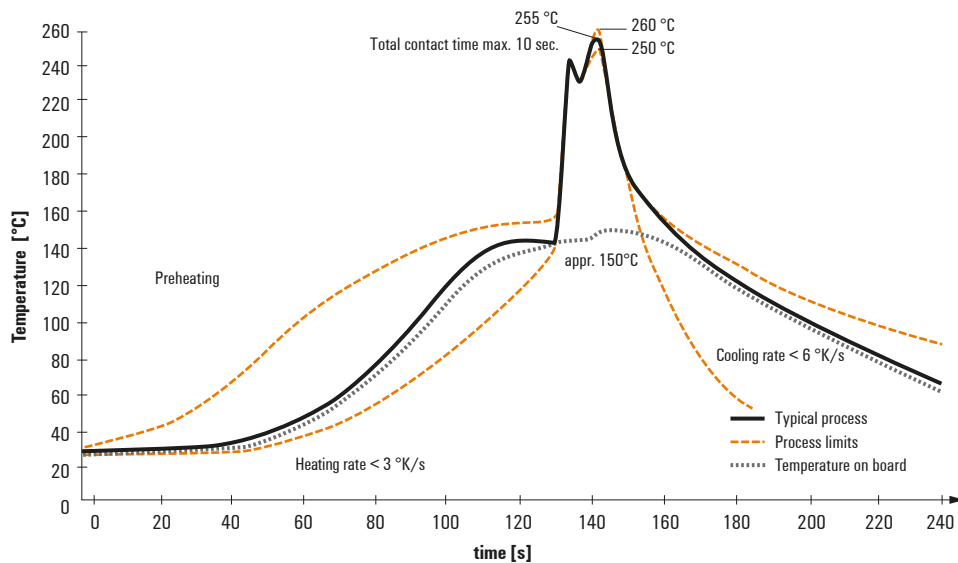
Recommended wave soldering profiles

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Single Wave:



Double Wave:



Wave soldering profiles

Wired connection elements should be processed in accordance with the DIN EN 61760-1 standard. We have included two recommendations for practical wave soldering profiles, with which Weidmüller PCB terminals and connectors are qualified.

When choosing a suitable profile for your application, the following factors also need to be considered:

- PCB thickness
- Proportion of Cu in the layers
- Single/double-sided assembly
- Product range
- Heating and cooling rates

The single and double wave profiles each indicate the recommended operating range, including the maximum soldering temperature of 260°C. In practice, the maximum soldering temperature is quite often well below the above maximum profile.

We reserve the right to make technical changes.

Recommended reflow soldering profile

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Klingenbergstraße 16

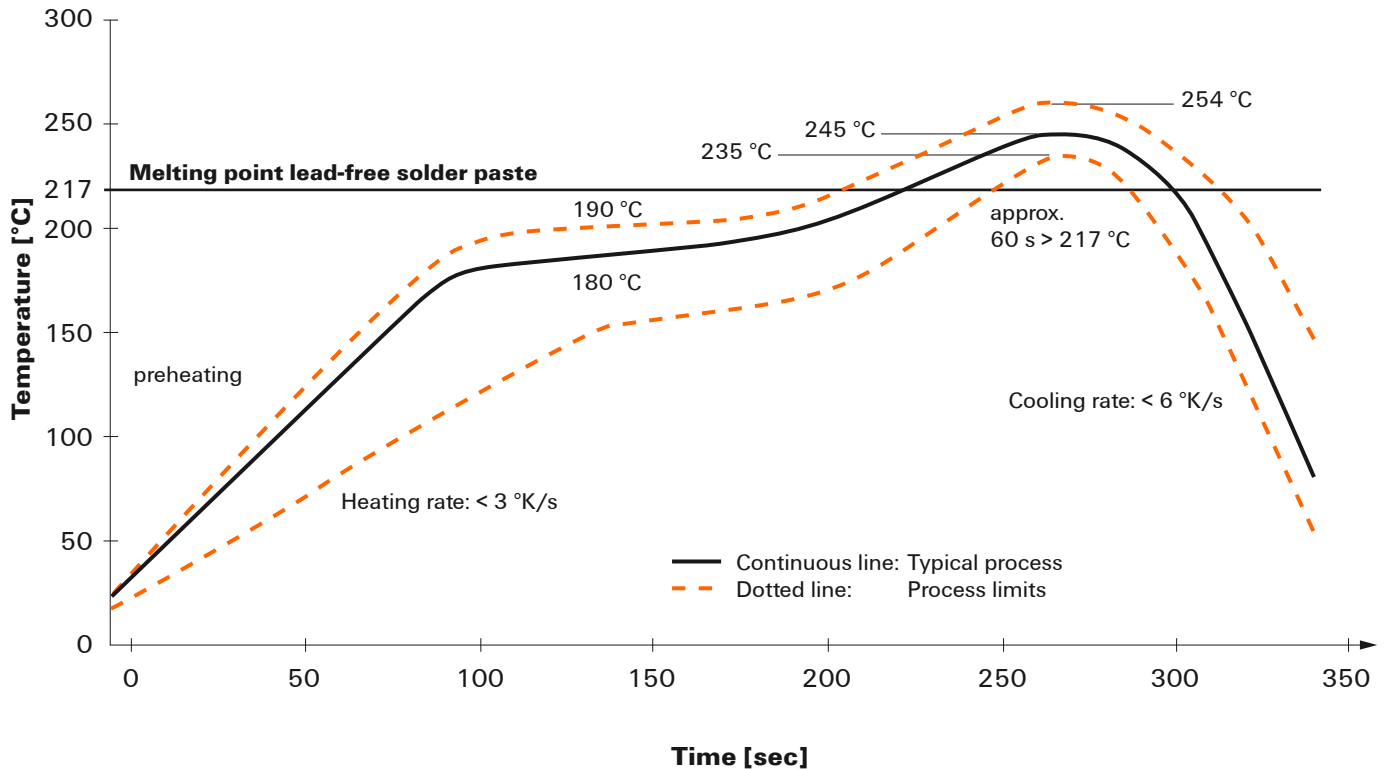
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Reflow soldering profile

The perfect soldering profile for SMT Surface Mount Technology is one the most exiting question in SMT production. But there are more than one correct answer: The diagram of temperature-on-time is related to processing features of solder paste and to maximum load of components.

We have to consider the following parameters:

- Time for pre heating
- Maximum temperature
- Time above melting point
- Time for cooling
- Maximum heating rate
- Maximum cooling rate

We recommend a typical solder profile with associated process limits. With preheating components and board are prepared smoothly for the solder phase. Heating rate is typically $\leq +3\text{K/s}$. In parallel the solder paste is 'activated'. The time above melting point of 217°C the paste gets liquid and components and boards begin to connect. The maximum temperature of 245°C to 254°C should stay between 10 and 40 seconds. In the cooling phase at $\geq -6\text{K/s}$ solder is cured. Board and components cool down while avoiding cold cracks.